PCN Number: 20231114001.1					PCN Date:	November 14, 2023			
Title: Qualification of CDAT as an additional Assembly site for select devices									
Customer Contact: Change Management Team Dept: Quality Services									
	Ī		_	nple request	s Dec 14,				
Proposed 1st Ship Date: Feb 12, 2024					ccepted unti				
*Sample requests received after Dec 14, 2023 will not be supported.									
Change Type:									
Assembly Site	<u>. </u>	☐ Desi	an	ПП	Material				
☐ Assembly Pro			Sheet	TH	☐ Wafer Bump Process				
Assembly Ma			number change						
☐ Mechanical S			Site		Wafer Fab M				
☐ Packing/Ship	•		Process		Wafer Fab Process				
		P	CN Details	•	•				
Description of C	hange:								
Texas Instrument	s Incorpora	ted is announci	ng the qualification	of CDA	AT as an addi	tional			
			Construction differe						
			TI Clar	k	CDAT				
Molo	l Compound		420862	5	4222198				
Reason for Chan	ge:								
Supply continuity	.90.								
Anticipated impa	act on Forr	n, Fit, Functio	n, Quality or Relia	bility (positive / ne	egative):			
None		, -,	, C ,		,				
Impact on Enviro	onmental E	Patings							
Impact on Livin	ommentar i	Cathigs							
Checked boxes in	dicate the s	status of enviro	nmental ratings foll	owing i	mplementatio	n of this			
_	boxes are c	hecked, there a	are no changes to t	he ass	ociated enviro	onmental			
ratings.									
RoHS		REACH			IEC	C 62474			
	\boxtimes	No Change	No Change ■ No Ch	е	No Change				
Changes to prod	luct identif	ication resulti	ng from this PCN:						
Assembly Site		ly Site Origin (22L)	igin Assembly Countr (23L)		Asse	embly City			
TI Clark			PHL		Angeles (City, Pampanga			
CDAT		CDA	CHN		CI	Chengdu			
Sample product s	hinning lahe	l (not actual r	aroduct label)						
Sample product shipping label (not actual product label)									
TEXAS	(P 6)		(1P) SN74LS07N	SR					
U4 PAINEXBURGAL:									
MADE IN: Malaysia (Q) 2000 (D) 0336 MSL 2 /260C/1 YEAR SEAL DT (31T) LOT: 3959047MLA									
MSL 1 /235C/UNLIM 03/29/04									
OPT: (P)									
LBL: 5A (L)T0:1750 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS									

Product Affected:				
DP83822HFRHBR	DP83822HRHBR	DP83822IFRHBR	DP83822IRHBR	
DP83822HFRHBT	DP83822HRHBT	DP83822IFRHBT	DP83822IRHBT	

TI Information Selective Disclosure

Qualification Report

Qualify DP83822x family full turnkey at CDAT (Asy and test) Approve Date 21-SEPTEMBER-2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: DP83822HFRHBT	QBS Reference: DP83826ERHBR	QBS Reference: DP83826ERHBR	QBS Reference: DP83822RHBT
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	0/0/0	0/0/0	0/0/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	1/77/0
HTOL	B1	Life Test	125C	1000 Hours	-	1/77/0	1/77/0	1/77/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	1/3/0	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	1/30/0

- QBS: Qual By Similarity
- Qual Device DP83822HFRHBT is qualified at MSL2 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: $\underline{\text{http://www.ti.com/}}$

TI Qualification ID: R-CHG-2201-055

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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